#### **REGISTRATION FORM**



FRAUNHOFER INSTITUTE FOR MICROELECTRONIC CIRCUITS AND SYSTEMS IMS

# **Hotel Booking**

Hotel rooms have been reserved at the Plaza Hotel. Please contact the hotel directly.

Date: November 6th to 7th

Keyword: »Fraunhofer/HighTemperature«

Price € 98,00 (breakfast included)

Address:

Hotel Plaza OHG Düsseldorfer Str. 54 47051 Duisburg

Tel.: +49 203 / 28 22 0 Fax: +49 203 / 28 22 300

www.hotel-plaza.de info@hotel-plaza.de

#### How to find us

http://www.inhaus.fraunhofer.de/en/about-us/Directions.html

Parking opportunities can be found on the nearby university car park in Carl-Benz-Strasse.

Name / First Na	me / Title
Affiliation	
Address	
Phone / Fax	
E-Mail	
Signature	

Please send this completed registration form by October 26<sup>th</sup>, 2012, at the latest. Fax: +49 203 3783-153 or Email: susanne.kittner@ims.fraunhofer.de

# Please note

Registrations are subject to space availability and will be confirmed only after fee payment!

### Workshop Fee

450 € (Registration before October 26<sup>th</sup>, 2012)
The workshop fee includes a USB memory stick (with presentations), lunches, and the evening event on November 6<sup>th</sup>, 2012.

350 € (Registration before October 5<sup>th</sup>, 2012)

#### Cancellations

Half of the payment will be reimbursed for cancellations received before October 26<sup>th</sup>, 2012. Later cancellations will not be reimbursed!

# Terms of Payment

After reception of the registration form, an invoice will be sent to the participants and the fee has to be transferred under reference of the invoice number until October 31<sup>st</sup>, 2012, at the latest. Payment by credit card is not possible.

#### Contact at Fraunhofer IMS:

Susanne Kittner Fraunhofer-inHaus-Center

Phone +49 203 / 3783-170 Forsthausweg 1

Fax +49 203 / 3783-153 D-47057 Duisburg

susanne.kittner@ims.fraunhofer.de Phone +49 203 / 713967-0

www.ims.fraunhofer.de www.inhaus.fraunhofer.de

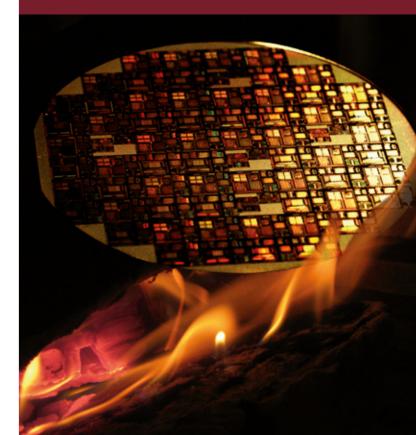
Location:

For further information see:

http://www.ims.fraunhofer.de/en/veranstaltungen.html

November 6<sup>th</sup> and 7<sup>th</sup>, 2012

# HIGH TEMPERATURE ELECTRONICS



# **Objectives and Scope**

High temperature electronics is a continuously growing market demanding for new technologies and concepts. Fraunhofer IMS hosts a workshop on HT electronics to provide a forum for industry and academia in this field. Follow interesting presentations on applications, circuit and system design, technologies and materials for HT applications and get in touch with users and technology providers.

# **Workshop Venue**

The workshop will be held at the Fraunhofer-inHaus-Center in Duisburg, which is located near the Fraunhofer IMS.

# **Organizing Committee**

Prof. Dr. Rainer Kokozinski, Holger Kappert, Dr. Uwe Paschen, Reneé Lerch and Norbert Kordas Assistance: Sigrid van Kempen and Susanne Kittner

#### Miscellaneous

During the breaks there will be tabletop exhibits. Furthermore you will have the opportunity to participate in a guided tour through the Fraunhofer IMS wafer fab as well as the labs of the inHaus-Center at the end of each day. A reception will take place at the Fraunhofer-inHaus-Center in the evening of November 6<sup>th</sup>.

# TUESDAY NOVEMBER 6th, 2012

10:00-10:15	<b>Welcome</b> Prof. Dr. Anton Grabmaier, Fraunhofer IMS	16:15-17:00	High temperature ICs in SOI CMOS technology Gonzalo Picun, X-REL Semiconductor SAS	11:45-12:30	Ceramic circuit boards with extended functions  Dr. Richard Matz, Siemens AG
APPLICATIONS		as of 17:00	Visit of IMS wafer fab and inHaus-Center	12:30-13:30	Lunch
10:15-11:00	Sensor applications	18:30	Reception at the inHaus-Center		
	Prof. Dr. Holger Fritze, TU Clausthal			PRINTED (	CIRCUIT BOARDS & MATERIALS
11:00-11:45	High temperature applications	WEDNESD	AY NOVEMBER 7 <sup>th</sup> , 2012	13:30-14:15	Cooling electronics with integrated
	for More Electrical Aircrafts:				heat carrier channels
	constraints, challenges and solutions	PASSIVES			Tobias Krühn, Leibniz Universität Hannover
	Dr. Olivier Crepel, EADS	9:00-09:45	Silicon capacitors with extremely high	14:15-15:00	Base materials for high temperature
	Régis Meuret, Hispano-Suiza		stability and reliability ideal for		printed circuit boards
11:45-12:30	RFID tags in high temperature applications		high temperature applications		Dr. Anna Exarchos, Isola GmbH
	Oliver Puetz-Gerbig, Balluff GmbH		Catherine Bunel, IPDiA	15:00-15.30	Break
12:30-13:30	Lunch	9:45-10:30	High temperature LTCC magnetic	15:30-16:15	Contact materials at elevated
			transformers and inductors		temperatures
SEMICONDUCTORS			Kai-Lars Riemenschneider, wts // electronic		Jörg Trodler, Heraeus Materials
13:30-14:15	Power semiconductors at extended		components GmbH for NASCENTechnology		Technology GmbH & Co. KG
	temperature, an overview		Manufacturing, INC.		
	Dr. Peter Friedrichs, Infineon Technologies AG	10:30-11:00	Break	RELIABILITY	
14:15-15:00	SiC integrated circuits			16:15-17:00	Reliability assessment for system
	David Clark, Raytheon UK	CERAMIC BOARDS			integration of high temperature
15:00-15:45	High temperature SOI technology	11:00-11:45	LTCC for harsh environment applications		electronics
	Dr. Uwe Paschen, Fraunhofer IMS		Thomas Bartnitzek, Micro-Hybrid		Dr. Olaf Wittler, Fraunhofer IZM
15:45-16:15	Break		Electronic GmbH	as of 17:00	Visit of IMS wafer fab and inHaus-Center